

Electronic Patent Application Fee Transmittal

Application Number:	10049270			
Filing Date:	27-Jun-2002			
Title of Invention:	MULTILAYER PRINTED WIRING BOARD, SOLDER RESIST COMPOSITION, METHOD FOR MANUFACTURING MULTILAYER PRINTED WIRING BOARD, AND SEMICONDUCTOR DEVICE			
First Named Inventor/Applicant Name:	Hui Zhong			
Filer:	Marvin Jay Spivak/Dalibor Tudman			
Attorney Docket Number:	312302US40PCT			
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Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
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